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Abstract

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10 The invention is related to a multi-chip-module and to a method for its manufacture. The module comprises a base carrier, on which at least in some areas signal conductor tracks and signal contact surfaces arranged at least in a single layer are located, and with at least one semiconductor component operating in the signal range

15 and connected with the signal conductor track and signal contact surfaces. The purpose is to achieve a high degree of integration with a multi-chip-module of this type. To do so, in addition at least in some areas on the base carrier power conductor tracks and power contact surfaces arranged in at least one layer are located. Furthermore, at least one power electronics component operating in the power range

is provided, which is connected with at least one power conductor track, at least one power contact surface and at least one signal conductor track. The power conductor tracks have a larger cross section than the signal conductor tracks at least on the basis of greater thickness dimensions.